

# RCJ050N25

## Nch 250V 5.0A Power MOSFET

$V_{DSS}$	250V
R <sub>DS(on)</sub> (Max.)	1360m $Ω$
I <sub>D</sub>	5.0A
$P_D$	30W

## ● Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

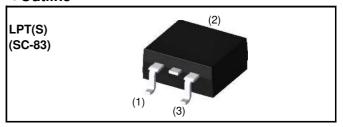
## Application

Switching Power Supply

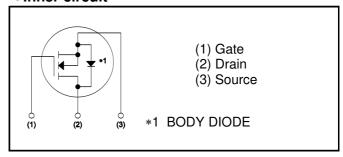
**Automotive Motor Drive** 

Automotive Solenoid Drive

#### Outline



## •Inner circuit



Packaging specifications

	ging opcomouncing	
	Packaging	Taping
	Reel size (mm)	330
Tuno	Tape width (mm)	24
Туре	Quantity (pcs)	1,000
	Taping code	TL
	Marking	RCJ050N25

# •Absolute maximum ratings( $T_a = 25$ °C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	$V_{ m DSS}$	250	V	
Continuous dusin suurent	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±5.0	A
Continuous drain current	T <sub>c</sub> = 100°C	I <sub>D</sub> *1	±2.7	А
Pulsed drain current	I <sub>D,pulse</sub> *2	±20	Α	
Gate - Source voltage	$V_{GSS}$	±30	V	
Avalanche energy, single pulse		E <sub>AS</sub> *3	1.82	mJ
Avalanche current		I <sub>AR</sub> *3	2.5	Α
T <sub>c</sub> = 25°C		$P_{D}$	30	W
Power dissipation $T_a = 25^{\circ}C^{^{*4}}$		$P_{D}$	1.56	W
Junction temperature	T <sub>j</sub>	150	°C	
Range of storage temperature		$T_{stg}$	-55 to +150	°C

## ●Thermal resistance

Parameter	Symbol	Values			Unit
Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	$R_{thJC}$	-	-	4.16	°C/W
Thermal resistance, junction - ambient *4	$R_{thJA}$	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# •Electrical characteristics( $T_a = 25$ °C)

Parameter	Symbol	Conditions		Values	Unit	
- Farameter	Зупівої	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$ , $I_D = 1mA$	250	-	1	V
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 250V, V_{GS} = 0V$ $T_j = 25^{\circ}C$	1	1	10	μА
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	1	±10	nA
Gate threshold voltage	V <sub>GS (th)</sub>	$V_{DS} = 10V$ , $I_D = 1mA$	3.5	-	5.5	V
		$V_{GS} = 10V, I_D = 2.5A$	-	970	1360	
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	$V_{GS} = 10V, I_D = 2.5A$ $T_j = 125^{\circ}C$	-	2100	2950	mΩ
Forward transfer admittance	g <sub>fs</sub>	$V_{DS} = 10V, I_{D} = 2.5A$	1.25	2.50	-	S

# • Electrical characteristics ( $T_a = 25$ °C)

Parameter	Cumbal	Conditions	Values			Unit
raiainetei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	-	350	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	30	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	15	-	
Turn - on delay time	$t_{d(on)}$ *5	$V_{DD} \simeq 125V, V_{GS} = 10V$	-	15	-	
Rise time	t <sub>r</sub> *5	$I_{D} = 2.5A$	-	16	-	no
Turn - off delay time	${t_{d(off)}}^{*5}$	$R_L = 49.9\Omega$	-	18	-	ns
Fall time	t <sub>f</sub> *5	$R_G = 10\Omega$	-	10	-	

# •Gate Charge characteristics( $T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
raiainetei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≃ 125V	-	8.5	-	
Gate - Source charge	${\sf Q_{gs}}^{*5}$	$I_{D} = 5.0A$	-	3.5	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	$V_{GS} = 10V$	-	3.5	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 125V, I_D = 5.0A$	-	8.0	-	V

## ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

Doromotor	Cumbal	Conditions	Values			Unit
Parameter	Symbol	Symbol Conditions -		Тур.	Max.	Offic
Continuous source current	l <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	-	5.0	Α
Pulsed source current	I <sub>SM</sub> *2	1 <sub>c</sub> = 23 0	-	-	20	Α
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_S = 5.0A$	-	-	1.5	٧
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 2.5A	-	90	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/μs	-	225	-	nC

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $^{\simeq}$  500 $\mu$ H,  $V_{DD}$  = 50V, Rg = 25 $\Omega$ , starting  $T_{j}$  = 25°C

<sup>\*4</sup> Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

<sup>\*5</sup> Pulsed

Fig.1 Power Dissipation Derating Curve

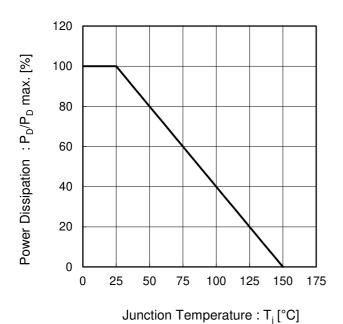
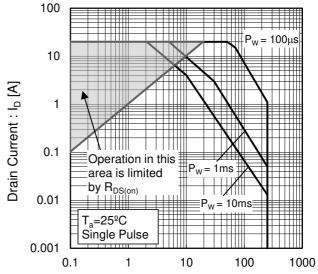
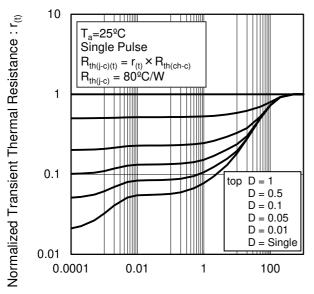


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width: Pw[s]

Fig.4 Avalanche Current vs Inductive Load

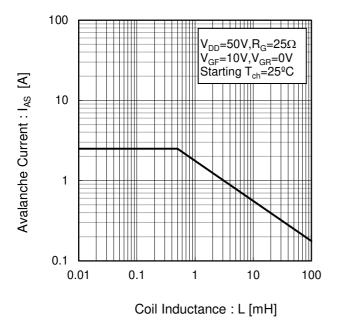


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature

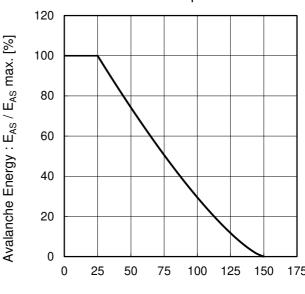
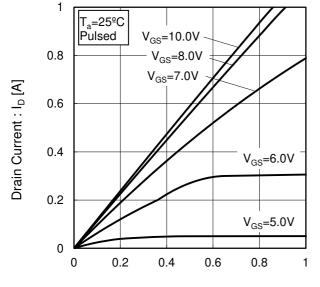


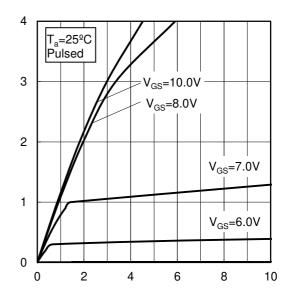
Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage :  $V_{DS}\left[V\right]$ 

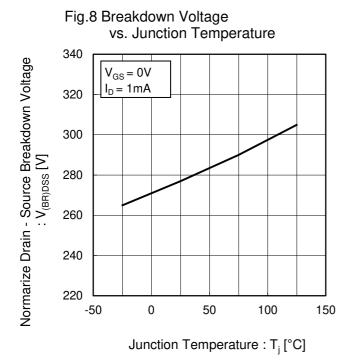
Fig.7 Typical Output Characteristics(II)

Junction Temperature : T<sub>i</sub> [°C]



Drain - Source Voltage : V<sub>DS</sub> [V]

Drain Current : I<sub>D</sub> [A]



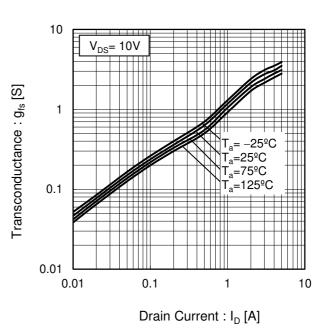
10  $V_{DS} = 10V$ 1 Drain Current : I<sub>D</sub> [A] 0.1 T<sub>a</sub>= 125ºC T<sub>a</sub>= 75°C T<sub>a</sub>= 25°C 0.01 0.001 2 3 5 8 9 10 4 6

Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.11 Transconductance vs. Drain Current

Fig.9 Typical Transfer Characteristics

Fig.10 Gate Threshold Voltage vs. Junction Temperature 5.5  $V_{DS} = 10V$  $I_D = 1mA$ Gate Threshold Voltage: V<sub>GS(th)</sub> [V] 5.0 4.5 4.0 3.5 3.0 2.5 -50 -25 25 50 75 100 125 150 Junction Temperature : T<sub>i</sub> [°C]





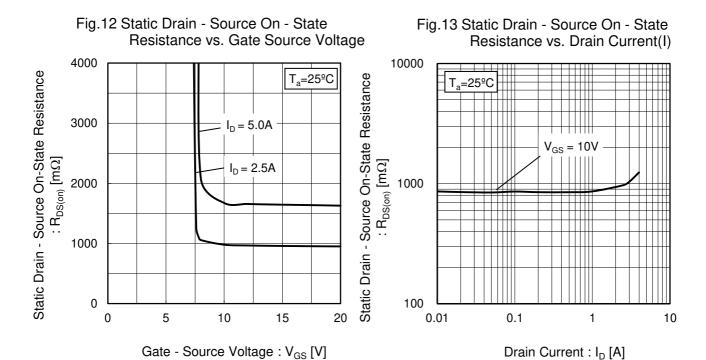


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature

Junction Temperature : T<sub>i</sub> [°C]

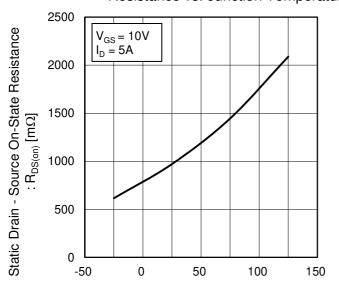


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

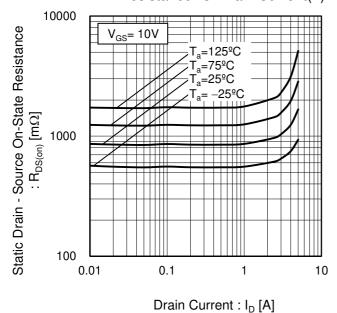
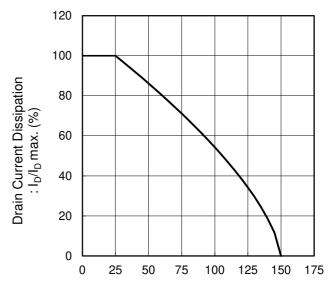
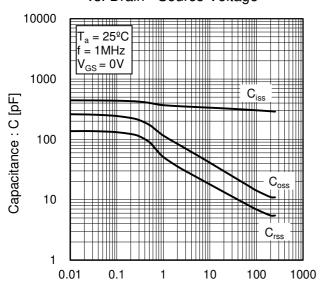


Fig.16 Drain Current Derating Curve



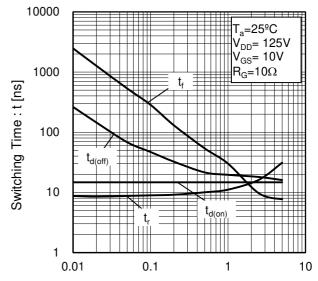
Junction Temperature : T<sub>i</sub> [°C]

Fig.17 Typical Capacitance vs. Drain - Source Voltage



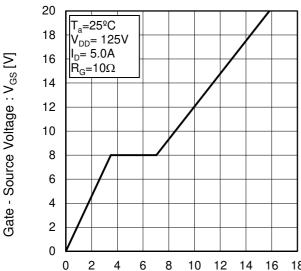
Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.18 Switching Characteristics

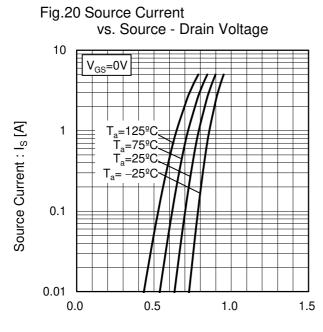


Drain Current: I<sub>D</sub> [A]

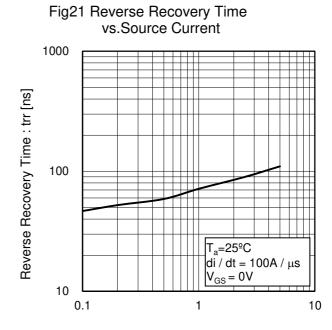
Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q<sub>g</sub> [nC]



Source-Drain Voltage :  $V_{SD}$  [V]



Source Current : I<sub>S</sub> [A]

## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

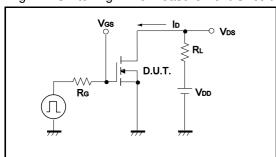


Fig.2-1 Gate Charge Measurement Circuit

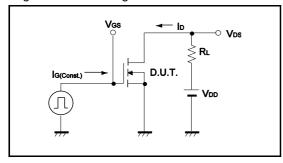


Fig.3-1 Avalanche Measurement Circuit

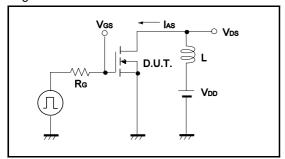


Fig.1-2 Switching Waveforms

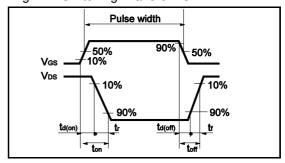


Fig.2-2 Gate Charge Waveform

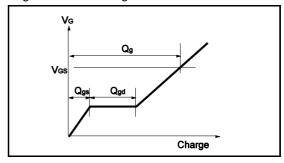
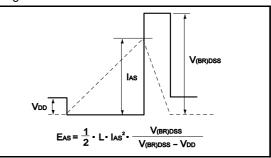
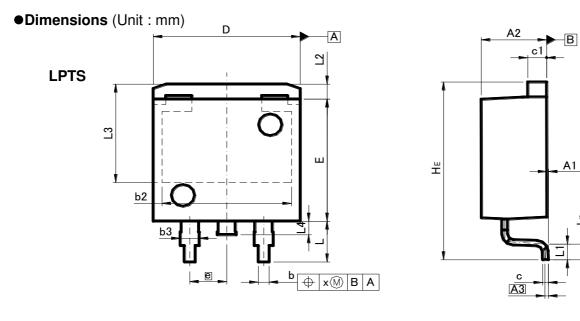
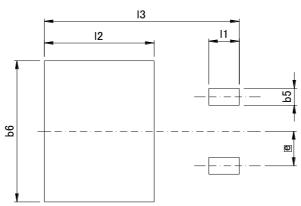


Fig.3-2 Avalanche Waveform







## Patterm of terminal position areas

DIM	MILIM	MILIMETERS		HES	
DIM	MIN	MAX	MIN	MAX	
A1	0.00	0.30	0	0.012	
A2	4.30	4.70	0.169	0.185	
A3	0.5	25	0.0	01	
b	0.68	0.98	0.027	0.039	
b2	8.	90	0.	35	
b3	1.14	1.44	0.045	0.057	
С	0.30	0.60	0.012	0.024	
c1	1.10	1.50	0.043	0.059	
D	9.80	10.40	0.386	0.409	
E	8.80	9.20	0.346	0.362	
е	2.	54	0.10		
HE	12.80	13.40	0.504	0.528	
L	2.70	3.30	0.106	0.13	
L1	0.90	1.50	0.035	0.059	
L2	1.	10	0.0	143	
L3	7.:	7.25		85	
L4	1.	00	0.0	39	
Lp	0.90	1.50	0.035	0.059	
Х	_	0.25	_	0.01	

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
b5	-	1.23	-	0.049
b6	ı	10.40	ı	0.409
11	ı	2.10	ı	0.083
12	-	7.55	-	0.297
13	-	13.40	-	0.528

Dimension in mm/inches

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CLASSⅢ	CL ACCTI	CLASS II b	СГУССШ
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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